



**PATENT APPLICATION**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Hyun-Woo Kim et al. Examiner: Amanda C. Walke  
Serial No: 10/787,368 Group Art Unit: 1752  
Filed: February 26, 2004 Docket: 8028-42 (SPX200304-0017US)  
For: **METHOD OF FORMING AN UNDERLAYER OF A BI-LAYER RESIST  
FILM AND METHOD OF FABRICATING A SEMICONDUCTOR  
DEVICE USING THE SAME**

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**RESPONSE**

Sir:

This paper is being filed in response to the Final Office Action mailed on May 16, 2006.

*Do Not Enter  
ACW 7/27/06*

**CERTIFICATE OF MAILING 37 C.F.R. §1.8(a)**

I hereby certify that this correspondence (and any document referred to as being attached or enclosed) is being deposited with the United States Postal Service as first class mail, postage paid in an envelope addressed to: Mail Stop AF, Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450, on July 11, 2006.

Dated:

7/11/06

  
Scott L. Appelbaum